

LS35

RELIABILITY DATA

DWG. No PA581-57-01		
APPD	CHK	DWG
<i>Jeg</i> 5-Jan-09	<i>Ramach</i> 5-Jan-09	<i>[Signature]</i> 5-Jan-09

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※ The above data is typical value. As all units have nearly the same characteristics, the data to be considered as ability value.

1. CALCULATED VALUES FOR MTBF

MODEL : LS35-5

1. Calculating Method

Calculated based on part count reliability projection of JEITA (RCR-9102).

Individual failure rates λ_G is given to each part and MTBF is calculated by the count of each part.

Formula :

$$\begin{aligned}
 \text{MTBF} &= \frac{1}{\lambda_{\text{equip}}} \\
 &= \frac{1}{\sum_{i=1}^n N_i (\lambda_G \pi_Q)_i} \times 10^6 \text{ (HOURS)}
 \end{aligned}$$

where :

λ_{equip} = Total Equipment Failure Rate (Failure / 10^6 Hours)

λ_G = Generic Failure Rate For The ith Generic Part (Failure / 10^6 Hours)

N_i = Quantity of ith Generic Part

n = Number of Different Generic Part Categories

π_Q = Generic Quality Factor for the ith Generic Part ($\pi_Q = 1$)

2. MTBF Values

G_F : (GROUND, FIXED)

MTBF = 706,464 (Hours)

2. Component derating

MODEL : LS35-5

(1) Calculating method

(a) Measuring Conditions

Input	: 115 , 230VAC	• Ambient temperature	: 50°C
Output	: 5V 10A(100%)	• Mounting method	: Mounting A

(b) Semiconductors

Compared with maximum junction temperature and actual one which is calculated based on case temperature, power dissipation and thermal impedance.

(c) IC, Resistors, Capacitors, etc.

Ambient temperature, operating condition, power dissipation and so on are within derating criteria.

(d) Calculating Method of Thermal Impedance

$$\theta_{j-c} = \frac{T_{j(\max)} - T_c}{P_{c(\max)}} \quad \theta_{j-a} = \frac{T_{j(\max)} - T_a}{P_{c(\max)}} \quad \theta_{j-l} = \frac{T_{j(\max)} - T_l}{P_{c(\max)}}$$

T_c : Case temperature at start point of derating ; 25°C in general

T_a : Ambient temperature at start point of derating ; 25°C in general

T_j : Lead temperature at start point of derating ; 25°C in general

$P_{c(\max)}$: Maximum collector(channel) dissipation
($P_{ch(\max)}$)

$T_{j(\max)}$: Maximum junction(channel) temperature
($T_{ch(\max)}$)

(θ_{j-c}) : Thermal impedance between junction(channel) and case
(θ_{ch-c})

θ_{j-a} : Thermal impedance between junction and air

θ_{j-l} : Thermal impedance between junction and lead

(2) Component Derating List

Location No.	Vin = 115VAC Load = 100% Ta = 50°C
Q3 STF6NK60ZFP ST MICROELECTRONICS	Tchmax = 150°C, $\theta_{ch-c} = 4.2^\circ\text{C/W}$, Pch = 0.964W, $\Delta T_c = 42.6^\circ\text{C}$, Tch = Tc + ((θ_{ch-c}) × Pch) = 96.65°C D.F. = 64.44% Pch(max) = 30W Tc = 92.6°C
D7 STPS20L45CFP ST MICROELECTRONICS	Tjmax = 150°C, $\theta_{j-c} = 3.5^\circ\text{C/W}$, Pd = 3.16W, $\Delta T_c = 74.6^\circ\text{C}$, Tj = Tc + ((θ_{j-c}) × Pd) = 135.67°C D.F. = 90.44% Tc = 124.6°C
D1 RS405M RECTRON	Tjmax = 150°C, $\theta_{j-c} = 6.0^\circ\text{C/W}$ Pd = 1.32W, $\Delta T_c = 30.3^\circ\text{C}$ Tj = Tc + ((θ_{j-c}) × Pd) = 88.22°C D.F. = 58.82% Tc = 80.3°C
D2 CRF02 TOSHIBA	Tjmax = 150°C, $\theta_{j-l} = 20^\circ\text{C/W}$ Pd = 0.06W, $\Delta T_l = 61.3^\circ\text{C}$ Tj = Tl + ((θ_{j-l}) × Pd) = 112.5°C D.F. = 75.0% Tl = 111.3°C
D4 CRH01 TOSHIBA	Tjmax = 150°C, $\theta_{j-l} = 20^\circ\text{C/W}$ Pd = 2.0mW, $\Delta T_l = 29.71^\circ\text{C}$ Tj = Tl + ((θ_{j-l}) × Pd) = 79.75°C D.F. = 53.17% Tl = 79.71°C
PC1 PS2561L2-E3(D)-A (TRANSISTOR) NEC	Tjmax = 125°C, $\theta_{j-c} = 150^\circ\text{C/W}$, Pc = 3mW, $\Delta T_c = 31.7^\circ\text{C}$, Tj = Tc + ((θ_{j-c}) × Pc) = 82.15°C D.F. = 65.72% Pc(max) = 0.15W Tc = 81.7°C
PC1 PS2561L2-E3(D)-A (LED) NEC	Tjmax = 125°C, $\theta_{j-c} = 150^\circ\text{C/W}$, Pc = 12mW, $\Delta T_c = 31.7^\circ\text{C}$, Tj = Tc + ((θ_{j-c}) × Pc) = 83.5°C D.F. = 66.8% Pc(max) = 0.15W Tc = 81.7°C
PC2 PS2561L2-E3(D)-A (TRANSISTOR) NEC	Tjmax = 125°C, $\theta_{j-c} = 150^\circ\text{C/W}$, Pc = 0.0W, $\Delta T_c = 36.3.1^\circ\text{C}$, Tj = Tc + ((θ_{j-c}) × Pc) = 86.3°C D.F. = 69.1% Pc(max) = 0.15W Tc = 86.3°C
PC2 PS2561L2-E3(D)-A (LED) NEC	Tjmax = 125°C, $\theta_{j-c} = 150^\circ\text{C/W}$, Pc = 0.0W, $\Delta T_c = 36.3.1^\circ\text{C}$, Tj = Tc + ((θ_{j-c}) × Pc) = 86.3°C D.F. = 67.28% Pc(max) = 0.15W Tc = 86.3°C
A1 FA13842N-D1-TE1 FUJI-ELEC.	Tjmax = 150°C, $\theta_{j-c} = 72^\circ\text{C/W}$ Pd = 0.108W, $\Delta T_c = 28.3^\circ\text{C}$ Tj = Tc + ((θ_{j-c}) × Pd) = 86.1°C D.F. = 57.39% Tc = 78.3°C
A2 HA17L431AP-TZ-E RENESAS	Tjmax = 150°C, $\theta_{j-c} = 100^\circ\text{C/W}$, Pd = 30.9mW, $\Delta T_c = 25.2^\circ\text{C}$, Tj = Tc + ((θ_{j-c}) × Pd) = 78.3°C D.F. = 52.20% Tc = 75.2°C
PD1 264-7GVD/S530-E2 EVERLIGHT	IF = 6.38mA, $\Delta T_c = 17.8^\circ\text{C}$ Allowable IF(max)= 12mA(at Ta = 67.8°C) D.F. = 53.17% Tc = 67.8°C


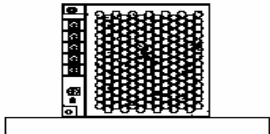
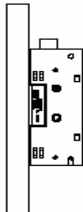
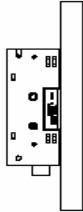
Component Derating List

Location No.	$V_{in} = 230VAC$ $Load = 100\%$ $T_a = 50^\circ C$
Q3 STF6NK60ZFP ST MICROELECTRONICS	$T_{chmax} = 150^\circ C$, $\theta_{ch-c} = 4.2^\circ C/W$, $P_{ch} = 1.18W$, $\Delta T_c = 43.8^\circ C$, $T_{ch} = T_c + ((\theta_{ch-c}) \times P_{ch}) = 98.76^\circ C$ $D.F. = 65.84\%$ $P_{ch(max)} = 30W$ $T_c = 93.8^\circ C$
D7 STPS20L45CFP ST MICROELECTRONICS	$T_{jmax} = 150^\circ C$, $\theta_{j-c} = 3.5^\circ C/W$, $P_d = 3.16W$, $\Delta T_c = 75.0^\circ C$, $T_j = T_c + ((\theta_{j-c}) \times P_d) = 136.06^\circ C$ $D.F. = 90.71\%$ $T_c = 125.0^\circ C$
D1 RS405M RECTRON	$T_{jmax} = 150^\circ C$, $\theta_{j-c} = 6.0^\circ C/W$ $P_d = 0.67 W$, $\Delta T_c = 22.0^\circ C$ $T_j = T_c + ((\theta_{j-c}) \times P_d) = 76.1^\circ C$ $D.F. = 50.68\%$ $T_c = 72.0^\circ C$
D2 CRF02 TOSHIBA	$T_{jmax} = 150^\circ C$, $\theta_{j-l} = 20^\circ C/W$ $P_d = 0.06W$, $\Delta T_l = 54.4^\circ C$ $T_j = T_l + ((\theta_{j-l}) \times P_d) = 105.6^\circ C$ $D.F. = 70.49\%$ $T_l = 104.4^\circ C$
D4 CRH01 TOSHIBA	$T_{jmax} = 150^\circ C$, $\theta_{j-l} = 20^\circ C/W$ $P_d = 2.0mW$, $\Delta T_l = 29.61^\circ C$ $T_j = T_l + ((\theta_{j-l}) \times P_d) = 79.65^\circ C$ $D.F. = 53.1\%$ $T_l = 79.61^\circ C$
PC1 PS2561L2-E3(D)-A (TRANSISTOR) NEC	$T_{jmax} = 125^\circ C$, $\theta_{j-c} = 150^\circ C/W$, $P_c = 2.75mW$, $\Delta T_c = 33.4^\circ C$, $T_j = T_c + ((\theta_{j-c}) \times P_c) = 83.82^\circ C$ $D.F. = 67.10\%$ $P_{c(max)} = 0.15W$ $T_c = 83.4^\circ C$
PC1 PS2561L2-E3(D)-A (LED) NEC	$T_{jmax} = 125^\circ C$, $\theta_{j-c} = 150^\circ C/W$, $P_c = 12mW$, $\Delta T_c = 33.4^\circ C$, $T_j = T_c + ((\theta_{j-c}) \times P_c) = 85.2^\circ C$ $D.F. = 68.20\%$ $P_{c(max)} = 0.15W$ $T_c = 83.4^\circ C$
PC2 PS2561L2-E3(D)-A (TRANSISTOR) NEC	$T_{jmax} = 125^\circ C$, $\theta_{j-c} = 150^\circ C/W$, $P_c = 0.0W$, $\Delta T_c = 39.1^\circ C$, $T_j = T_c + ((\theta_{j-c}) \times P_c) = 89.1^\circ C$ $D.F. = 71.28\%$ $P_{c(max)} = 0.15W$ $T_c = 89.1^\circ C$
PC2 PS2561L2-E3(D)-A (LED) NEC	$T_{jmax} = 125^\circ C$, $\theta_{j-c} = 150^\circ C/W$, $P_c = 0.0W$, $\Delta T_c = 39.1^\circ C$, $T_j = T_c + ((\theta_{j-c}) \times P_c) = 89.1^\circ C$ $D.F. = 71.28\%$ $P_{c(max)} = 0.0W$ $T_c = 89.1^\circ C$
A1 FA13842N-D1-TE1 FUJI-ELEC.	$T_{jmax} = 150^\circ C$, $\theta_{j-c} = 72^\circ C/W$ $P_d = 0.103W$, $\Delta T_c = 28.6^\circ C$ $T_j = T_c + ((\theta_{j-c}) \times P_d) = 86.2^\circ C$ $D.F. = 57.35\%$ $T_c = 78.6^\circ C$
A2 HA17L431AP-TZ-E RENESAS	$T_{jmax} = 150^\circ C$, $\theta_{j-c} = 100^\circ C/W$, $P_d = 30.6mW$, $\Delta T_c = 26.2^\circ C$, $T_j = T_c + ((\theta_{j-c}) \times P_d) = 79.26^\circ C$ $D.F. = 52.84\%$ $T_c = 76.2^\circ C$
PD1 264-7GVD/S530-E2 EVERLIGHT	$I_F = 6.38mA$, $\Delta T_c = 18.4^\circ C$ Allowable $I_F(max) = 12mA$ (at $T_a = 68.4^\circ C$) $D.F. = 53.17\%$ $T_c = 68.4^\circ C$

3. Main components temperature rise ΔT list

MODEL : LS35-5

Condition:

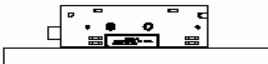
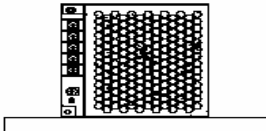
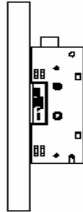
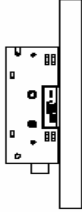
Standard Mounting (Mounting Method (A))	(A)			
				
	Mounting A	Mounting B	Mounting C	Mounting D
Input Voltage (VAC)	115			
Output Voltage (VDC)	5			
Output Current (A)	7			

Output Derating $T_a = 50^\circ\text{C}$		ΔT Temperature rise ($^\circ\text{C}$)			
		$I_o=100\%$	$I_o=100\%$	$I_o=100\%$	$I_o=100\%$
Location No	Parts Name	Mounting (A)	Mounting (B)	Mounting (C)	Mounting (D)
Q3	MOSFET	42.6	42.3	38.9	57.0
D1	BRIDGE DIODE	30.3	46.7	30.6	36.5
D7	F.R. DIODE	74.6	72.8	72.5	68.7
A1	CHIP IC	28.3	29.4	25.7	41.1
A2	SHUNT REGULATOR	25.2	30.3	44.4	22.0
PC1	PHOTOCOUPLER	31.7	34.7	31.6	42.4
PC2	PHOTOCOUPLER	36.3	38.8	36.3	44.6
F1	FUSE	18.6	26.8	27.9	17.0
L1	BALUN COIL	36.4	41.6	37.2	33.5
L2	CHOKE COIL	41.3	45.8	50.5	35.6
C3	CAP. FILM	31.5	36.0	35.0	28.1
C8	CAP. ELECT.	23.3	33.1	21.3	30.2
C25	CAP. ELECT.	28.7	29.1	26.5	43.6
C26	CAP. ELECT.	23.5	25.8	21.8	40.7
C29	CAP. ELECT.	50.1	46.4	46.4	41.5
C30	CAP. ELECT.	42.2	42.2	43.4	35.5
C31	CAP. ELECT.	43.3	43.1	45.2	35.6
C32	CAP. ELECT.	33.8	38.0	41.2	28.3

3. Main components temperature rise ΔT list

MODEL : LS35-5

Condition:

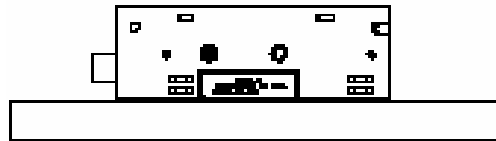
Standard Mounting (Mounting Method (A))	(A)			
				
	Mounting A	Mounting B	Mounting C	Mounting D
Input Voltage (VAC)	230			
Output Voltage (VDC)	5			
Output Current (A)	7			

Output Derating $T_a = 50^\circ\text{C}$		ΔT Temperature rise ($^\circ\text{C}$)			
		$I_o=100\%$	$I_o=100\%$	$I_o=100\%$	$I_o=100\%$
Location No	Parts Name	Mounting (A)	Mounting (B)	Mounting (C)	Mounting (D)
Q3	MOSFET	43.8	44.4	40.7	58.3
D1	BRIDGE DIODE	22.0	40.3	22.6	36.5
D7	F.R. DIODE	75.0	73.4	73.0	68.7
A1	CHIP IC	28.6	30.0	25.7	42.0
A2	SHUNT REGULATOR	26.2	31.7	47.1	22.7
PC1	PHOTOCOUPLER	33.4	36.3	33.9	44.5
PC2	PHOTOCOUPLER	39.1	41.7	39.8	47.7
F1	FUSE	15.5	25.3	23.6	14.2
L1	BALUN COIL	24.3	33.6	25.9	22.7
L2	CHOKER COIL	43.4	49.3	52.8	37.4
C3	CAP. FILM	23.4	31.2	26.7	21.2
C8	CAP. ELECT.	18.8	30.8	17.3	24.9
C25	CAP. ELECT.	29.2	30.0	27.3	44.6
C26	CAP. ELECT.	23.7	26.3	22.3	41.5
C29	CAP. ELECT.	50.1	47.9	47.5	42.1
C30	CAP. ELECT.	42.1	43.6	44.0	35.7
C31	CAP. ELECT.	43.7	44.6	45.8	35.9
C32	CAP. ELECT.	33.9	39.8	41.6	28.5

4. Electrolytic capacitor lifetime

MODEL : LS35-5

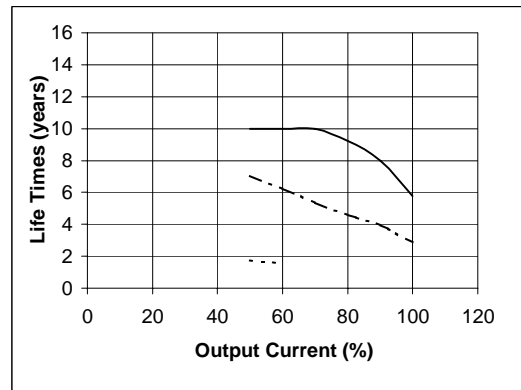
Mounting A



Ta = 40°C ———
 = 50°C - - - - -
 = 70°C ·····

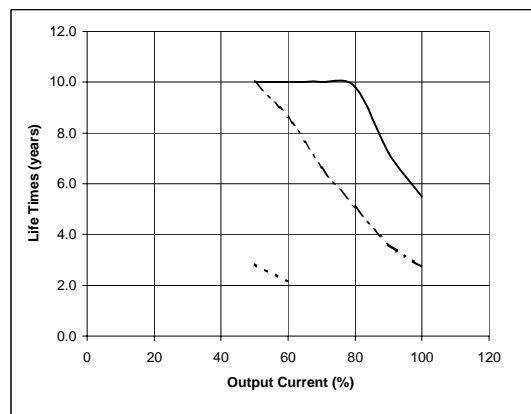
Vin = 115VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	7.1	1.8
60	10.0	6.2	1.6
70	10.0	5.4	—
80	9.2	4.6	—
90	8.0	4.0	—
100	5.8	2.9	—



Vin = 230VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	10.0	2.8
60	10.0	8.6	2.2
70	10.0	6.6	—
80	9.8	5.1	—
90	7.2	3.6	—
100	5.5	2.7	—

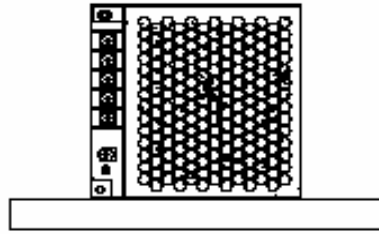


Note : E-cap life calculation is based on 8hrs/day operation.

4. Electrolytic capacitor lifetime

MODEL : LS35-5

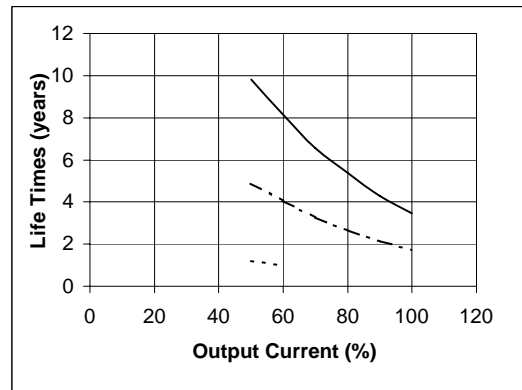
Mounting B



Ta = 40°C ———
 = 50°C - - - -
 = 70°C ·····

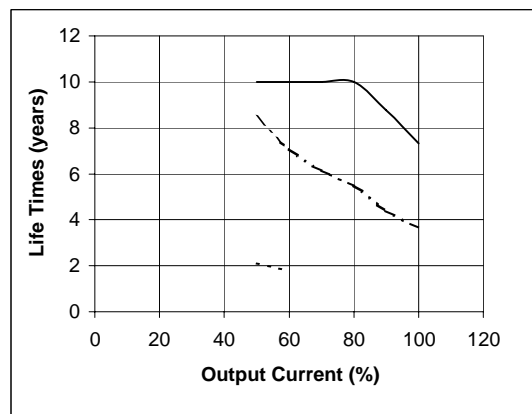
Vin = 115VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	9.8	4.9	1.2
60	8.1	4.1	1.0
70	6.6	3.3	—
80	5.4	2.7	—
90	4.3	2.1	—
100	3.5	1.7	—



Vin = 230VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	8.5	2.1
60	10.0	7.1	1.8
70	10.0	6.2	—
80	10.0	5.5	—
90	8.8	4.4	—
100	7.3	3.7	—

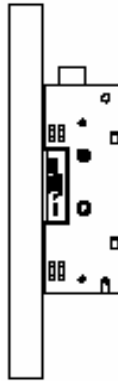


Note : E-cap life calculation is based on 8hrs/day operation.

4. Electrolytic capacitor lifetime

MODEL : LS35-5

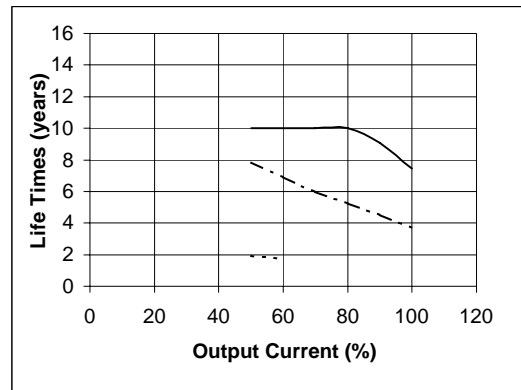
Mounting C



Ta = 40°C ———
 = 50°C - - - - -
 = 70°C ·····

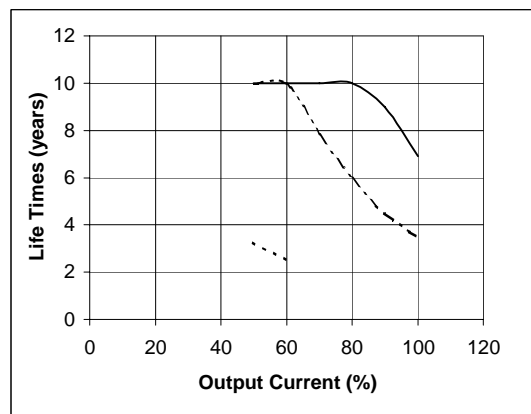
Vin = 115VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	7.9	2.0
60	10.0	6.9	1.7
70	10.0	6.0	—
80	10.0	5.3	—
90	9.1	4.5	—
100	7.5	3.7	—



Vin = 230VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	10.0	3.2
60	10.0	10.0	2.5
70	10.0	7.8	—
80	10.0	6.0	—
90	9.0	4.5	—
100	6.9	3.5	—

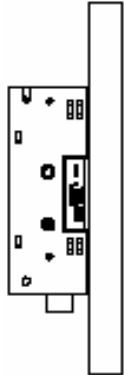


Note : E-cap life calculation is based on 8hrs/day operation.

4. Electrolytic capacitor lifetime

MODEL : LS35-5

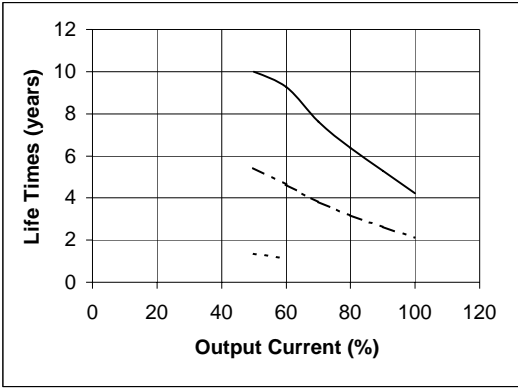
Mounting D



Ta = 40°C ———
 = 50°C - - - - -
 = 70°C - - - - -

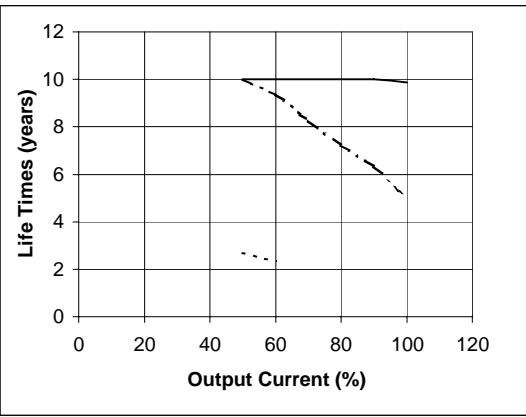
Vin = 115VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	5.4	1.4
60	9.3	4.6	1.2
70	7.6	3.8	—
80	6.4	3.2	—
90	5.3	2.6	—
100	4.2	2.1	—



Vin = 230VAC

Load (%)	Life Time (years)		
	Ta = 40°C	Ta = 50°C	Ta = 70°C
50	10.0	10.0	2.7
60	10.0	9.3	2.3
70	10.0	8.2	—
80	10.0	7.2	—
90	10.0	6.3	—
100	9.9	4.9	—



Note : E-cap life calculation is based on 8hrs/day operation.

5. Vibration Test

MODEL : LS35-5

(1) Vibration Test Class

Frequency Variable Endurance Test

(2) Equipment Used

Controller : F-400-BM-E47 (EMIC CORP.)
 Vibrator : 905-FN (EMIC CORP.)
 Serial no. : 22965

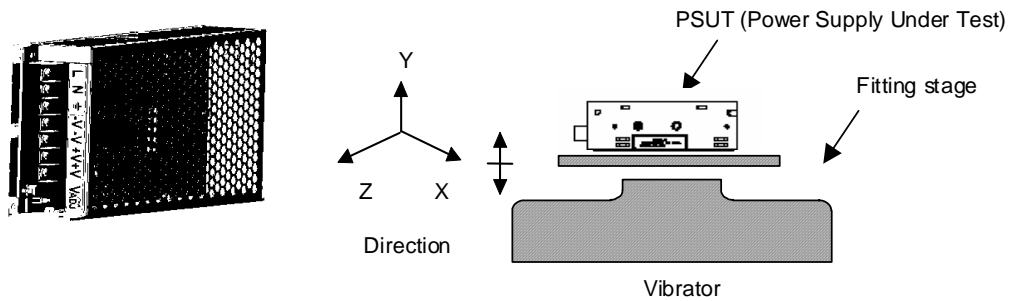
(3) The Number Of D.U.T. (Device Under Test)

1 Unit

(4) Test Conditions

Sweep Frequency : 10 - 55Hz Direction : X, Y, Z
 Sweep Time : 1 minute Test Time : 1 hour each axis
 Acceleration : 2G Non-operation
 Mounting : A and B

(5) Test Method



Fix the PSUT on the universal plate via two M3 tapped holes on the chassis of the power supply. Standard mounting position as per test specification.

(6) Test results - OK

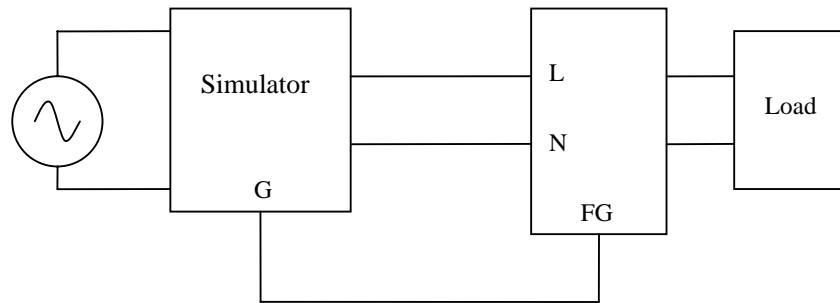
Test Conditions : Vin = 230 Vac Load Condition :
 Ambient Temp. = +25 °C Full Load

Check Item		Output Voltage (V)	PSUT State
Before Test		Vo1	
		5.046	
After test	X	5.046	OK
	Y	5.046	OK
	Z	5.046	OK

6. Noise simulate test

MODEL : LS35-5

(1) Test circuit and equipment



Simulator : INS-400L Noise Laboratory Co.,LTD

(2) Test conditions

- | | | | |
|-----------------------|----------------|------------------|-----------------|
| • Input voltage | : 115, 230VAC | • Noise level | : 0V~2.4kV |
| • Output voltage | : Rated | • Phase shift | : 0° ~ 360° |
| • Output current | : 0%, 100% | • Polarity | : +, - |
| • Ambient temperature | : 25°C | • Mode | : Normal Common |
| • Pulse Width | : 0ns ~ 1000ns | • Trigger select | : Line |

(3) Acceptable conditions

1. Not to be broken.
2. No output shutdown.
3. No other out of order.

(4) Test result O K

7. Abnormal test

MODEL : LS35-5

(1) Test Condition

Input Voltage : 230VAC Output Current : 100% Ta : 25°C, 70% RH

(2) Test Results

(Da: Damaged)

No.	Test Position		Test Mode		Test Results												NOTE
	LOCATION	TEST POINT	S H O R T	O P E N	1	2	3	4	5	6	7	8	9	10	11	12	
					F I R E	S M O K E	B U R S T	S M E L H O T	R E D H O T	D A M A G E B L O W	F U S E B L O W	O C P P P P	O V P P	N O O U T P U T	N O C H A N G E	O T H E R	
1	D1	(+) - (-)	•								•	•			•		Da : F1
2	D2		•								•				•		Da : Q3, Z1, Z2
3	D3		•												•		
4	D4		•												•		
5	D5		•												•		
6	D6		•								•					•	Hiccup, Da : R31,R30
7	D7		•								•				•		No Damage
8	Q1	3 - 4	•												•	•	Da : A1,Q3,Z1,Z2
				•												•	Latch
		1 - 6	•												•	•	Latch
		3 - 5	•												•	•	Latch
		6 - 2	•												•	•	Latch
9	Q2	C - E	•												•		Hiccup
		B - E	•												•		Hiccup
		C - B	•												•		Hiccup
10	Q3	G - S	•											•			Da : Z1,F1
		D - G	•								•	•		•			Da : F1,Q3,Z2
11	C8	(+)Bulk - (-)Bulk	•								•	•		•			Da : F1
12	C20		•											•			Da : Q3,F1,Z2
13	C21/R22	C21/R22	•								•	•		•			Da : Q3,Z2
		C21		•											•		
		R22		•											•		
14	C37 OR C38		•												•		Hissing sound
15	PC1	1 - 2	•										•	•		•	Latch
		3 - 4	•											•			Latch
		1 - 2		•									•	•		•	Latch
		3 - 4		•									•	•		•	Latch
16	PC2	3 - 4	•										•	•		•	Latch
		1 - 2	•												•		

7. Abnormal test

MODEL : LS35-5

(1) Test Condition

Input Voltage : 230VAC Output Current : 100% Ta : 25°C, 70% RH

(2) Test Results

(Da: Damaged)

No.	Test Position		Test Mode		Test Results												NOTE	
	LOCATION	TEST POINT	S H O R T	O P E N	1	2	3	4	5	6	7	8	9	10	11	12		
					F I R E	S M O K E	B U R S T	S M E L H O T	R E D H O T	D A M A G E	F U S E B L O W	O C P P P P P	O V P P P	N O O U T P U T	N O H A N G E	O T H E R		
17	A1	Vcc - GND	•											•				
		Vref - GND	•											•				
		Isense - GND	•							•				•				Da : Q3,Z2
		RtCt - GND	•											•				
		FB - GND	•												•			
		Comp - GND	•												•			
		Out - GND	•												•			
18	A2	A - K	•													•	Hiccup	
		R - K	•													•	Vo = 4.39V	
		R - A	•											•		•	Latch	
19	T1	Np	•													•	Hiccup	
		Nbias	•													•	Hiccup	
		Ns	•													•	Hiccup	
20	PD1	•													•			
21	Z1	•												•				
22	Z2	•														•	Hissing sound	
		•														•		
23	Z4	•														•		
		•														•		
24	R9/C10	R9/C10	•											•				
		R9		•												•		
		C10		•												•		
25	R27	•								•	•		•			Da : Z1,F1,Q3		
27	R29	•								•			•				Da : Q3,Z1	
		•								•			•				Hissing sound	
28	R32	•														•	Hiccup	
		•														•	Latch	
29	R46	•											•	•		•	Latch	
		•											•	•		•	Latch	
30	VR1	•														•	Vo = 5.8	
		•														•	Vo = 2.9	

8. Thermal shock test

MODEL : LS35

(1) Equipment used

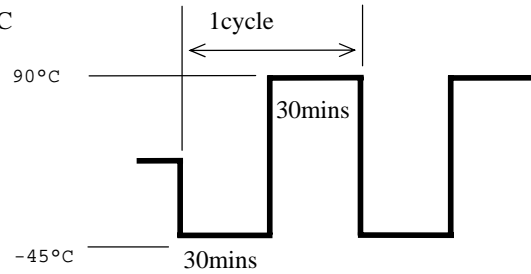
THERMAL SHOCK CHAMBER TSA-101S-W (ESPEC CORP.)

(2) The number of D.U.T.(Device Under Test)

1 unit

(3) Test Conditions

- Ambient temperature : -45°C ↔ 90°C
- Test time : 30 mins each temp.
- Test cycle : 100 cycles
- Not operating



(4) Test Method

Before testing, check if there is no abnormal output, then put the D.U.T. in testing chamber, and test it according to the above cycle. 100 cycles later, leave it for 1 hour at the room temperature, then check if there is no abnormal output.

(5) Test Results OK

Vin : 230VAC			5V			
Io : 100%			From		To	
Ripple&Spike noise		mV	17		31	
Line regulation	Full load	mV	1		1	
Load regulation	Vin:115V	mV	8		8	
Efficiency	Pin	W	43.95	79.3%	43.77	79.8%
	Vout	V	4.98		4.99	
	Iout	A	7		7	
Solder condition • etc.			—————		OK	